



1 Product profile

1.1 General description

Two planar PIN diodes in common cathode configuration in a SOT23 small plastic SMD package.

1.2 Features and benefits

- Two elements in common cathode configuration in a small-sized plastic SMD package
- Low diode capacitance
- Low diode forward resistance

1.3 Applications

General RF application

2 Pinning information

Table 1.	Discrete pinning		
Pin	Description	Simplified outline	Graphic symbol
1	anode		
2	anode		3
3	common cathode	1 2 Top view	1 2 aaa-029921



3 Ordering information

Table 2. Ordering information					
Type number Package					
	Name	Description	Version		
BAP50-05	-	plastic surface-mounted package; 3 leads	SOT023		

4 Marking

Table 3. Marking code	
Type number	Marking code
BAP50-05	1C%

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _R	continuous reverse voltage		-	50	V
IF	continuous forward current		-	50	mA
P _{tot}	total power dissipation	T _{sp} ≤ 90 °C	-	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
R _{th(j-sp)}	thermal resistance from junction to solder point		220	K/W

7 Characteristics

Table 6. Characteristics

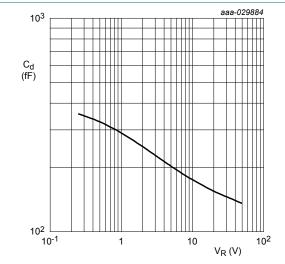
 T_i = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Мах	Unit
V _F	forward voltage	I _F = 50 mA		-	0.95	1.1	V
V _R	reverse voltage	I _R = 10 μA		50	-	-	V
I _R	reverse current	V _R = 50 V		-	-	100	nA
C _d	diode capacitance	f = 1 MHz (see <u>Figure 1</u>)					
		V _R = 0 V		-	0.45	-	pF
		V _R = 1 V		-	0.35	0.6	pF
		V _R = 5 V		-	0.3	0.5	pF
r _D	diode forward resistance	f = 100 MHz (see <u>Figure 2</u>)					
		I _F = 0.5 mA	[1]	-	25	40	Ω
		I _F = 1 mA	[1]	-	14	25	Ω
		I _F = 10 mA	[1]	-	3	5	Ω

[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.

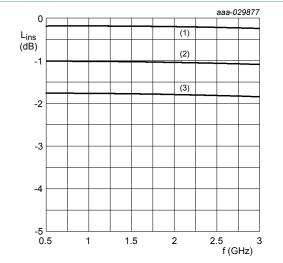
BAP50-05 Silicon PIN diode

8 Graphical data



f = 1 MHz; T_i = 25 °C.

Figure 1. Diode capacitance as a function of reverse voltage (typical values)



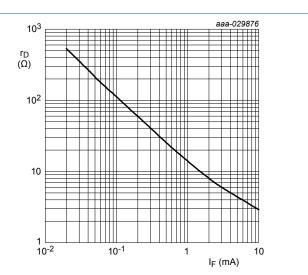
Diode inserted in series with a 50 Ω strip line circuit and biased via the analyzer T-network. T_{amb} = 25 °C.

(1) I_F = 10 mA

(2) $I_F = 1 \text{ mA}$

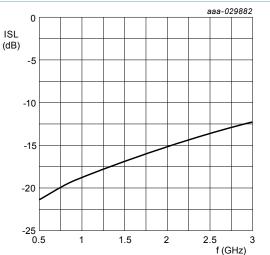
(3)
$$I_F = 0.5 \text{ mA}$$

Figure 3. Insertion loss of the diode as a function of frequency (typical values)



f = 100 MHz; T_i = 25 °C.

Figure 2. Diode forward resistance as a function of forward current (typical values)



Diode zero biased and inserted in series with a 50 Ω strip line circuit. T_{amb} = 25 °C.

Figure 4. Isolation of the diode as a function of frequency (typical values)

9 Package outline

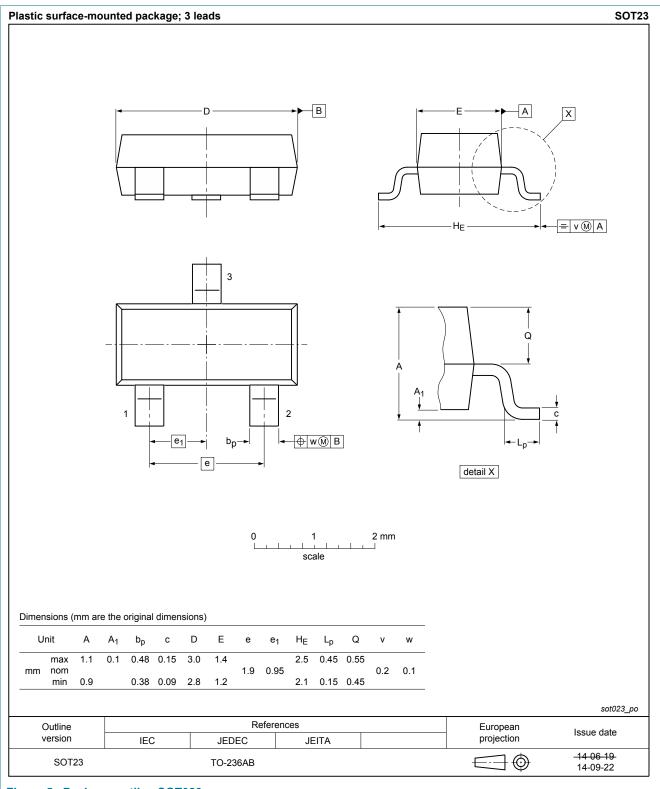


Figure 5. Package outline SOT023

BAP50-05 Product data sheet

10 Abbreviations

Acronym	Description
AQL	acceptable quality level
PIN	P-type, intrinsic, N-type
RF	radio frequency
S4	special inspection level 4
SMD	surface-mounted device

11 Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes		
BAP50-05 v.3.1	20190208	Product data sheet	-	BAP50-05 v.3		
Modifications:	aligned the title of the data sheet with the description on the Internet					
BAP50-05 v.3	20181126	Product data sheet	-	BAP50-05 v.2.1		
Modifications:	 <u>Section 1.2</u> "Features and benefits" has been updated. The "Legal information" pages have been updated. 					
BAP50-05 v .2.1	19990510	Product data sheet	-	BAP50-05 v.1		

12 Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

Please consult the most recently issued document before initiating or completing a design. [1]

[2] [3] The term 'short data sheet' is explained in section "Definitions".

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BAP50-05

Silicon PIN diode

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